
A Vacuum-Bonding Process for Packaging of High Temperature Microreactors

Personnel

J. Chou and L. Arana (K.F. Jensen and M.A. Schmidt)

Sponsorship

MURI

We are developing a process technology for the packaging of microchemical reactors in a vacuum environment. Such packages are extremely useful in applications where one would like to achieve isolation of heated microstructures to maximize efficiency. We have developed a process based upon low temperature bonding using an inorganic intermediate material. Experiments are on-going to characterize the vacuum sealing level of the bond, as well as to explore the use of getter materials.
